

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
26 December 2019 (26.12.2019)



(10) International Publication Number
WO 2019/245364 A1

(51) International Patent Classification:
H01L 21/56 (2006.01) *H01L 23/31* (2006.01)
B29C 45/14 (2006.01)

(21) International Application Number:
PCT/NL2019/050374

(22) International Filing Date:
18 June 2019 (18.06.2019)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2021145 18 June 2018 (18.06.2018) NL

(71) Applicant: **BESI NETHERLANDS B.V.** [NL/NL]; Ratio
6, 6921 RW Duiven (NL).

(72) Inventor: **KERSJES, Sebastianus Hubertus Maria**; c/o
Ratio 6, 6921 RW Duiven (NL).

(74) Agent: **PATENTWERK B.V.**; Mr. J.S.F. HOEBEN, P.O.
Box 1514, 5200 BN 's-Hertogenbosh (NL).

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH,

(54) Title: MOULD FOR ENCAPSULATING ELECTRONIC COMPONENTS, INSERT FOR SUCH A MOULD, METHOD FOR PRODUCING AN INSERT AND METHOD FOR ENCAPSULATING ELECTRONIC COMPONENTS

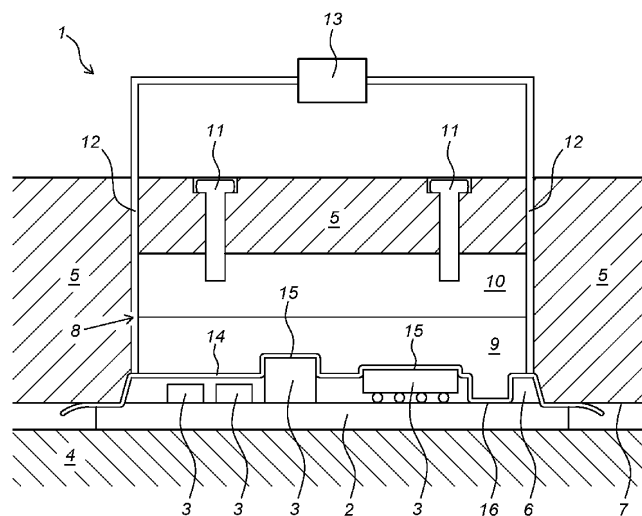


Fig. 1

(57) Abstract: The invention relates to a mould for encapsulating electronic components mounted on a carrier, comprising at least two mould parts which are displaceable relative to each other, at least one of the mould parts with a mould cavity recessed in a contact side, which mould parts are configured to engage with the mould cavity round the electronic components to be encapsulate, wherein at least a part of the mould cavity is formed by an insert having a flexible three-dimensional moulding surface facing the electronic components. The invention further relates to an insert for use in said mould and a method for encapsulating electronic components mounted on a carrier using said mould.

[Continued on next page]

WO 2019/245364 A1

GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))